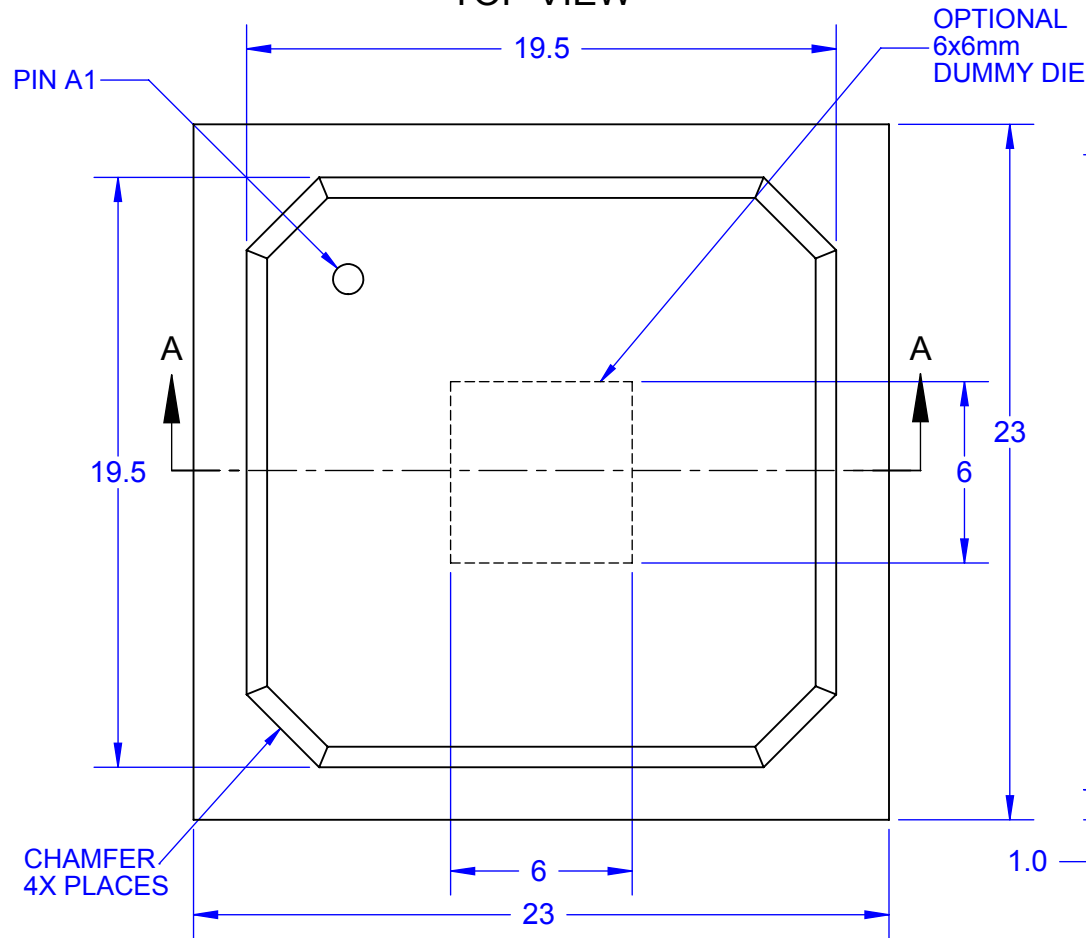
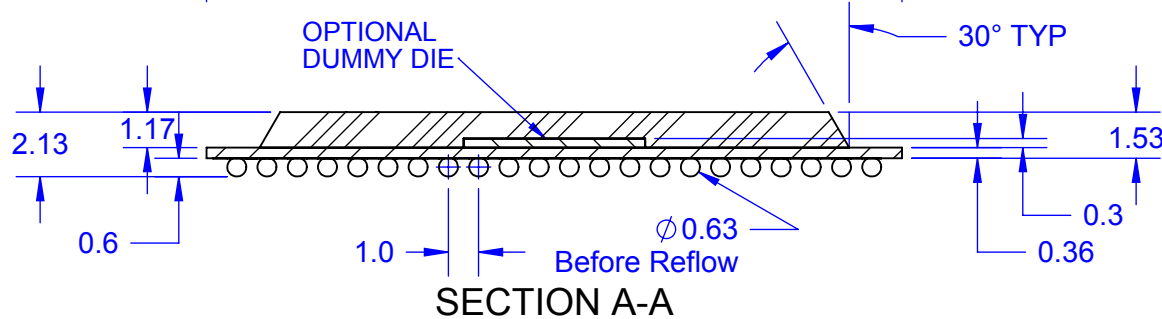
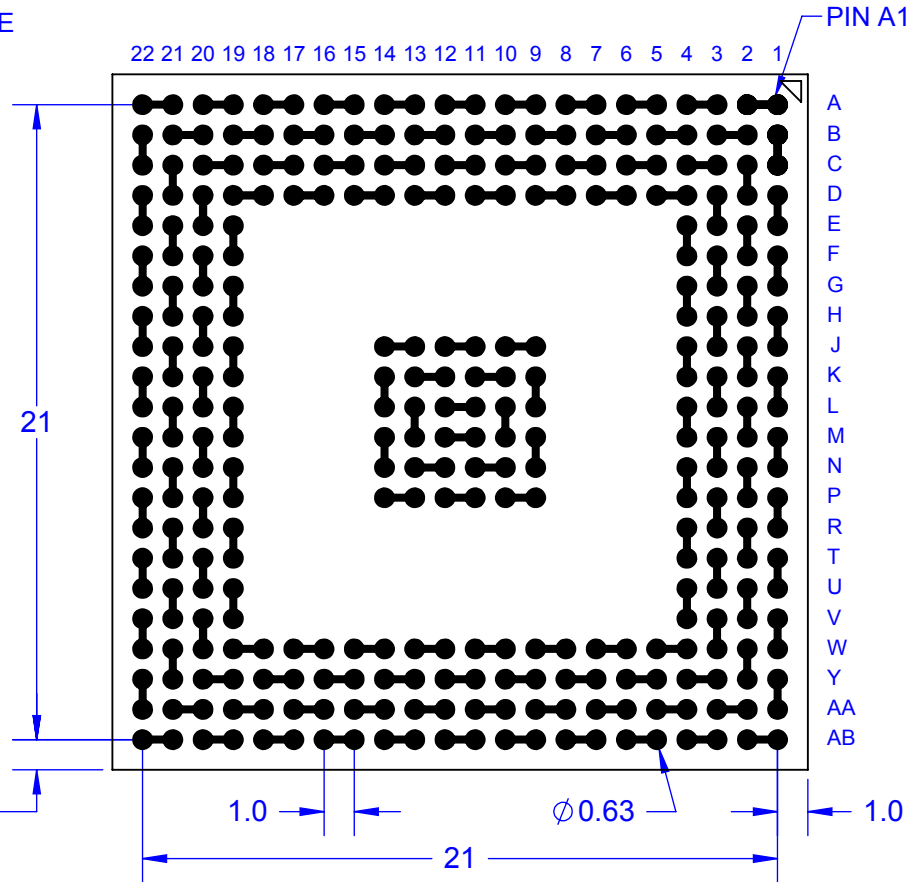


TOP VIEW



BALL VIEW



Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.63mm (25 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.508 (20 MIL).
- 5) PAD Cu DIAMETER: 0.635 (25 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

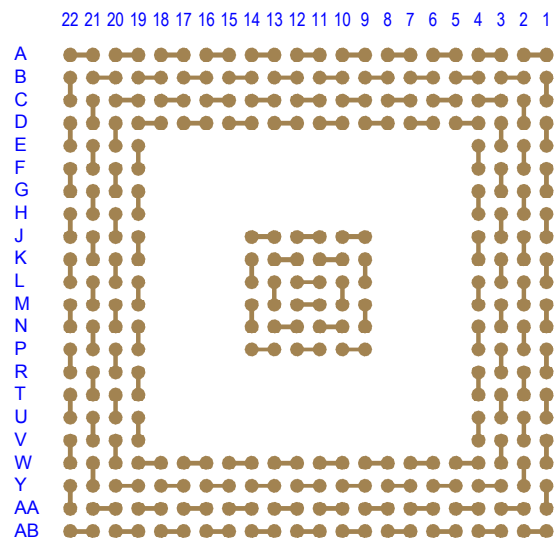
SECTION A-A

PART NUMBER TABLE

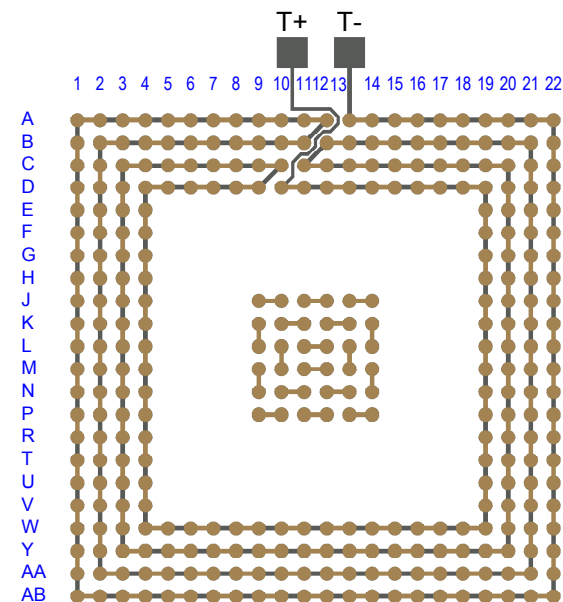
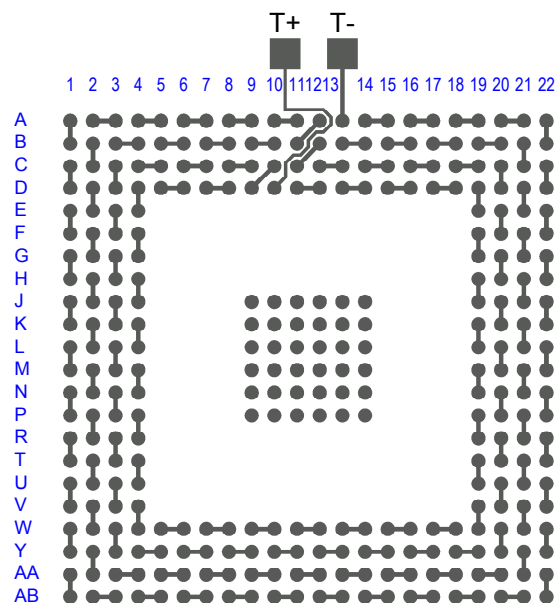
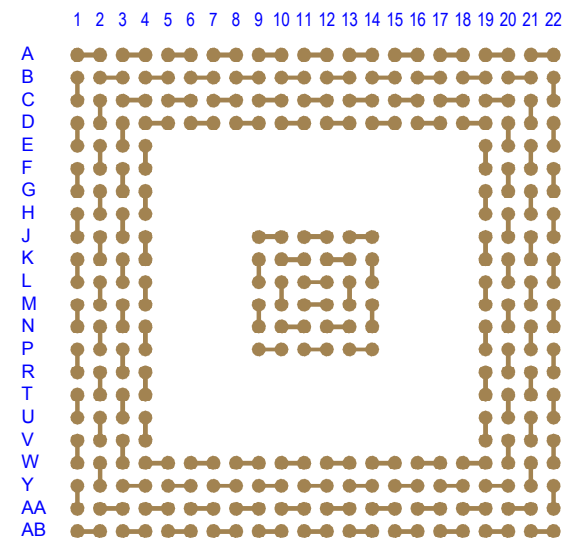
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA324T1.0C-DC224D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA324T1.0-DC224D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE				
DRAWN T.Au	3/25/13				
ENG M. Hart	3/25/13	TITLE BGA324T1.0C-DC224D DAISY CHAIN DUMMY			
MFG					
QA		SCALE 4:1	SIZE A	DRAWING NO. 512244	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			
					SHEET 1 OF 2

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD

AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.635 (25 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.203 (8 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.508 (20 MIL).

TopLine®

TITLE BGA324T1.0C-DC224D
DAISY CHAIN DUMMY

SCALE 4:1	SIZE A	DRAWING NO. 512244	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 2